

Reference 40nm Design Rule Manual

Process-1P10M 0.9V-1.8V-2.5V-3.3V, Logic (G)

Version 0.4

Dated:- 23rd Feb 2011

Notes: Note1 Manufacturing Grid is 0.005um or 5nm
 Note2 Design rule number with an 'R' are recommended rules
 Note3 All values are in microns unless specified otherwise

Layer	Rule Number	Description	Reference 40nm Value (um)
NWELL			
	nwell.w.1	Min Width	0.350
	nwell.s.1	min space and notch	0.350
	nwell.s.3	min space to N+ diff	0.090
	nwell.s.3.1	min space to N+ diff (at least one edge at each corner)	0.180
	nwell.s.3.2	min space to Pwell Strap	0.090
	nwell.ex.3	min extension over P+ diff	0.090
	nwell.ex.3.1	min extension over P+ diff (at least one edge at each corner)	0.180
	nwell.ex.3.2	min extension over Nwell(Nplus) Strap	0.090
	nwell.a.1	min area	0.810
	nwell.a.2	min enclosed area	0.810
DIFF			
	diff.w.1	Min Width	0.070
	diff.w.1R	Min Width recommended	0.100
	diff.w.2	min mosfet channel width	0.140
	diff.w.3	max mosfet channel width	10.000
	diff.w.4	max mosfet channel width for core PMOS devices	2.000
	diff.w.5	Minimum mosfet channel width for thick oxide devices	0.300
	diff.s.1	min space to diff	0.090
	diff.s.1R	min space and notch recommended	0.120
	diff.s.2	min space to diff is (w> 0.12um) and (CR>= 0.14um)	0.100
	diff.s.2.1	min space to diff is (w> 0.12um) and (CR>= 0.14um) IN POLY gate direction	0.120
	diff.s.3	net separation between the strap and the diffusion	0.150
	diff.ex.1	min extension over Poly	0.070
	diff.ex.1R	Recommended extension over Poly	0.120
	diff.a.1	min area	0.030
	diff.a.3	min enclosed area	0.044
	diff.L.1	Length of 45-degree bent Diffusion (minimum edge length)	0.300
	diff.L.2	maximum diff length of core device	10.000
	diff.dn.1	diff density across full chip	>=25%, <75%
POLY			

	poly.w.1	min width	0.040
	poly.w.2	max poly width	20.000
	poly.w.3	min gate length and allowed length	0.04/0.045/0.05/0.06/0.07/0.08~10
	poly.w.4	max gate length	12.000
	poly.w.5	min gate length for thick oxide devices	0.160
	poly.s.1	min space poly	0.080
	poly.s.1.R	min space poly recommended	0.100
	poly.s.1.1	Poly gate space range to neighbouring POLY or Dummy Poly (For channel length < 0.08)	0.15/0.17/0.22
	poly.s.1.2	min poly gate space	0.150
	poly.s.3	gate to gate space [If either mosfet length] ≥ 0.08	0.140
	poly.s.4	Maximum gate space [If either mosfet length] ≥ 0.08 to neighboring Poly or dummy poly in core devices	0.300
	poly.s.5	poly to diff space (for field poly)	0.035
	poly.s.6	poly space to L-shape diff	0.120
	poly.s.6R	poly space to L-shape diff Recommended	0.150
	poly.s.7	L-shape poly space diff	0.050
	poly.s.7R	L-shape poly space diff Recommended	0.120
	poly.s.10	Space if at least one {POLY or dummy POLY} width > 0.12um and the {POLY or Dummy Poly} parallel run length > 0.14um	0.160
	poly.s.11	Space {in the same RPO}	0.170
	poly.s.12	Space at line end	0.120
	poly.s.13	Large Poly to gate Space	1.000
	poly.l.1	min poly edge length	0.090
	poly.l.3	maximum length of the Poly between two contacts	20.000
	poly.ex.1	poly extension over diff (mosfet poly endcap)	0.100
	poly.ex.1R	poly extension over diff (mosfet poly endcap) Recommended	0.120
	poly.ex.2	poly extension over diff (mosfet poly endcap) if poly space to L-shaped diff is < 0.10	0.100
	poly.ex.2R	maximum recommended poly extension over diff (mosfet poly endcap)	0.300
	poly.ex.3	poly extension over rpoly	0.220
	poly.a.1	min poly area	0.025
	poly.a.2	min poly area if all edges < 0.21	0.060
	poly.a.3	min poly enclosed area	0.050
	poly.dn.1	Poly Density across full chip	$\geq 14\% \leq 50\%$
	poly.sglv.1	Gate with Width < 0.180um needs to covered by with dummy poly layer	
	poly.sglv.2	Gate with Width < 0.180um extended by 0.02um from the edges of the diffusion requires having another GATE/Poly/dummypoly adjacent to it satisfying poly.s.4 rule	
	poly.sglv.3	dummy poly layer to poly spacing	0.15/0.17/0.22
	poly.R.1	Gate Bends Not Allowed	
	poly.R.2	45 degree bends are not allowed for poly	
RPOLY			
	rpoly.w.1	min width	0.360

	rpoly.s.1	min space	0.360
	rpoly.s.2	min spacing from contact to rpoly	0.200
	rpoly.s.3	min spacing from poly to rpoly	0.200
	rpoly.s.4	min spacing from diffusion to rpoly	0.200
	rpoly.ex.1	min Extension of RPOLY over POLY	0.200
	rpoly.ex.2	min extension of rpoly over diffusion	0.200
	rpoly.ex.3	min overlap over P-plus	0.050
	rpoly.ex.4	min overlap over N-plus	0.050
	rpoly.a.1	min area	0.950
	rpoly.a.2	min Enclosed Area	0.950

PPLUS

	pplus.w.1	min width	0.200
	pplus.s.1	min space	0.200
	pplus.s.2	min space to diff	0.060
	pplus.s.3	min space to abutted Nplus	0.000
	pplus.s.4	min space to strap diff (not abutted)	0.030
	pplus.s.5	pplus over diff space to gate	0.090
	pplus.ex.1	pplus extension of poly	0.090
	pplus.ex.2	pplus extension of diff	0.090
	pplus.ex.3	pplus extension of strap diff	0.030
	pplus.ex.4	pplus extension over contact	0.030
	pplus.a.1	min area	0.080
	pplus.a.2	min enclosed area	0.080

NPLUS

	nplus.w.1	min width	0.200
	nplus.s.1	min space	0.200
	nplus.s.2	min space to diff	0.060
	nplus.s.3	min space to abutted Pplus	0.000
	nplus.s.4	min space to strap diff (not abutted)	0.030
	nplus.s.5	nplus over diff space to gate	0.090
	nplus.ex.1	nplus extension of poly	0.090
	nplus.ex.2	nplus extension of diff	0.090
	nplus.ex.3	nplus extension of strap diff	0.030
	nplus.ex.4	nplus extension over contact	0.030
	nplus.a.1	min area	0.080
	nplus.a.2	min enclosed area	0.080

LOWVTN

	lowvtn.w.1	min width	0.200
	lowvtn.s.1	min space	0.200
	lowvtn.s.2	space to gate in poly endcap dir	0.120
	lowvtn.s.3	space to gate in diff s/d direction	0.120
	lowvtn.ex.1	extension over gate in diff s/d dir	0.120
	lowvtn.ex.2	extension over gate in poly endcap dir	0.120
	lowvtn.a.1	min area	0.210
	lowvtn.a.2	min enclosed area	0.210

LOWVTP

	lowvtp.w.1	min width	0.200
	lowvtp.s.1	min space	0.200
	lowvtp.s.2	space to gate in poly endcap dir	0.120
	lowvtp.s.3	space to gate in diff s/d direction	0.120
	lowvtp.ex.1	extension over gate in diff s/d dir	0.120

	lowvtp.ex.2	extension over gate in poly endcap dir	0.120
	lowvtp.a.1	min area	0.210
	lowvtp.a.2	min enclosed area	0.210

HIGHVTN

	highvtn.w.1	min width	0.200
	highvtn.s.1	min space	0.200
	highvtn.s.2	space to gate in poly endcap dir	0.120
	highvtn.s.3	space to gate in diff s/d direction	0.120
	highvtn.ex.1	extension over gate in diff s/d dir	0.120
	highvtn.ex.2	extension over gate in poly endcap dir	0.120
	highvtn.a.1	min area	0.210
	highvtn.a.2	min enclosed area	0.210

HIGHVTP

	highvtp.w.1	min width	0.200
	highvtp.s.1	min space	0.200
	highvtp.s.2	space to gate in poly endcap dir	0.120
	highvtp.s.3	space to gate in diff s/d direction	0.120
	highvtp.ex.1	extension over gate in diff s/d dir	0.120
	highvtp.ex.2	extension over gate in poly endcap dir	0.120
	highvtp.a.1	min area	0.210
	highvtp.a.2	min enclosed area	0.210

DIFF18

	diff18.w.1	min width	0.320
	diff18.s.1	min space	0.320
	diff18.ex.1	min extension over gate	0.350
	diff18.ex.2	min extension over diff	0.300

DIFF25

	diff25.w.1	min width	0.320
	diff25.s.1	min space	0.320
	diff25.ex.1	min extension over gate	0.350
	diff25.ex.2	min extension over diff	0.300

DIFF33

	diff33.w.1	min width	0.320
	diff33.s.1	min space	0.320
	diff33.ex.1	min extension over gate	0.350
	diff33.ex.2	min extension over diff	0.300

CONT

	cont.w.1	width, maximum = minimum	0.060
	cont.s.1	min space	0.080
	cont.s.1R	recommended min Center to Center spacing	0.210
	cont.s.2	min space if 3 or more contacts within 0.11um	0.110
	cont.s.3	min space if contacts on different net	0.120
	cont.s.4	cont space to gate	0.045
	cont.s.4R	cont space to gate recommended	0.060
	cont.s.5	cont (inside poly) space to diff	0.060
	cont.s.6R	Recommended cont (inside poly) space to cont (inside diff) when CR > 0	0.170

	cont.s.6.1R	Recommended cont(inside poly) space to cont (inside diff) when CR = 0	0.150
	cont.ex.1	diff extension over cont	0.010/0.030
	cont.ex.1.R	diff extension over cont Recommended	0.010/0.040
	cont.ex.2	diff extension over cont four sides	0.020
	cont.ex.3	poly extension over cont	0.010/0.03
	cont.ex.3R	poly extension over cont	0.010/0.040
	cont.ex.4	polyextension over cont four sides	0.060
	cont.R.1	45 degree rotated Contacts not allowed	
	cont.R.2	Recommended minimum number of cuts for mosfets with width > 2um	2.000

M1

	m1.w.1	min width	0.070
	m1.w.2	max width	5.000
	m1.s.1	min space m1-m1	0.080
	m1.s.1R	min space m1-m1 Recommended	0.100
	m1.s.1.1R	min space m1-m1 Recommended for same net	0.130
	m1.s.3	min space m1-m1 if w> 0.17 and CR > 0.27	0.100
	m1.s.4	min space m1-m1 if w> 0.24 and CR > 0.27	0.120
	m1.s.5	min space m1-m1 if w> 0.31 and CR > 0.4	0.140
	m1.s.6	min space m1-m1 if w> 0.62 and CR > 0.62	0.210
	m1.s.7	min space m1-m1 if w> 1.5 and CR > 1.5	0.500
	m1.s.8	min space at line end (dense line end)if W < 0.090; CR length > 0.090um	0.080
	m1.ex.1	m1 extension over cont	0.00/0.030
	m1.ex.1R	m1 extension over contRecommended	0.03/0.05
	m1.ex.3	m1 extension over cont (four sides)	0.020
	m1.ex.3R	m1 extension over cont (four sides) recommended	0.030
	m1.ex.4	m1 extension over cont if m1 W > 0.7	0.030
	m1.ex.5	m1 extension over cont if m1 W > 0.11 ; sep to M1 < 0.08 ; CR to m1 >0.27	0.015
	m1.a.1	min area	0.0225
	m1.a.1.R	min area Recommended	0.0325
	m1.a.2	min enclosed area	0.220
	m1.l.1	Concave/Convex corner rule	0.070
	m1.dn.1	Metal density range	>=10% <=75%

Vx (where x=1-9)

	vx.w.1	min width	0.070
	vx.s.1	min space	0.080
	vx.s.2	min space with 3 neighboring vias within 0.11 distance	0.110
	vx.s.3	min space to vx of different net	0.100
	vx.ex.1	mx extension over vx	0.00/0.04
	vx.ex.1R	mx extension over vx Recommended	0.05/0.05
	vx.ex.2	mx extension over vx (4 sides)	0.025
	vx.ex.4	m1 extension over v1 if M1 w > 0.11 & sep < 0.8 & CR > 0.27	0.020
	vx.st.1	Via stacking allowed for vx and V(x+1)	
	vx.R.1	45 degree rotated via is not allowed	
	vx.R.2	Atleast two Viav with space <= 0.3 are required to connect Mx and M(x+1), when either of the two metals has a width and length >= 0.7	

	vx.R.3	Recommended maximum consecutive stacked Vx layer, which has only one via for each Vx layer to avoid high Rc. Rule not applicable to top via (V8 and V9)	3.000
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Mx (where x=2-10)

	mx.w.1	min width	0.070
	mx.w.2	max width	5.000
	mx.s.1	min space mx-mx	0.090
	mx.s.1R	min space mx-mx Recommended	0.100
	mx.s.3	min space mx-mx if w> 0.17 and CR > 0.27	0.100
	mx.s.4	min space mx-mx if w> 0.24 and CR > 0.27	0.120
	mx.s.5	min space mx-mx if w> 0.31 and CR > 0.4	0.150
	mx.s.6	min space mx-mx if w> 0.62 and CR > 0.62	0.210
	mx.s.7	min space mx-mx if w> 1.5 and CR > 1.5	0.500
	mx.s.8	min space at line end (dense line end)if W < 0.1; CR length > 0.035um	0.110
	mx.ex.1	mx extension over vx	0.000/0.040
	mx.ex.1R	mx extension over vx Recommended	0.000/0.050
	mx.ex.3	mx extension over vx (four sides)	0.025
	mx.ex.4	mx extension over vx if mx W > 0.6	0.300
	mx.ex.5	mx extension over vx if mx W > 0.6 ; sep to mx < 0.09 ; CR to mx >0.30	0.050
	mx.a.1	min area	0.030
	mx.a.1.R	min area recommended	0.035
	mx.a.2	min enclosed area	0.220

VARMARKER

	var.w.1	moscap min channel length	0.180
	var.w.2	high voltage moscap min channel length	0.360
	var.w.3	moscap min channel width	0.300
	var.s.1	min space to Active region	0.120
	var.a.1	Maximum core (not hv) varactor gate area (um2)	20.000
	var.ex.1	min enclosure with diffusion region	0.150
	var.r.1	varmarker layer must be drawn to fully cover varactor device	

RESISTOR RULES

	np.s.6	space to P type unsalicated OD/PO resistor	0.120
	np.ex.5	extension of n-type unsalicated OD/PO resistor	0.130
	res.w.1	Width of unsalicated OD/PO resistor	0.450
	res.l.1	Length of unsalicated OD/PO resistor	0.500
	res.r.1	Square (length/width) for OD/PO resistor	>=1
	res.ex.1	Resistor marker enclosure of unsalicated/salicated OD/PO resistor	0.180

***Mos specific rules can be found in DIFF and POLY sections.**

Notes